

**PATENT**

**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

**In re Application of:**

Luo et al.

**Serial No.:** 10/826,985

**Filed:** April 19, 2004

**For:** METHODS FOR FORMING  
PROTECTIVE LAYERS ON  
SEMICONDUCTOR DEVICE  
COMPONENTS SO AS TO REDUCE OR  
ELIMINATE THE OCCURENCE OF  
DELAMINATION THEREOF AND  
CRACKING THEREIN

**Confirmation No.:** 3493

**Examiner:** J. Stark

**Group Art Unit:** 2823

**Attorney Docket No.:** 2269-5565.1US  
(02-1124.01/US)

**VIA ELECTRONIC FILING**  
**November 21, 2007**

**AMENDMENT**

Mail Stop Amendment  
Commissioner for Patents  
PO Box 1450  
Alexandria, VA 22313-1450

Examiner:

This Amendment follows the Office Action of August 21, 2007, the shortened statutory period for response to which expires on November 21, 2007.

A listing of claims, in which amendments to the claims are presented, begins on page 2 of this paper; and

Remarks start at page 7 of this paper.